

**What is claimed is:**

1. A method of making an innerlayer panel, comprising:  
5           providing a metallic foil;  
             forming at least one fiducial over the foil;  
             forming at least one feature over the foil;  
             applying a dielectric over the at least one feature and over the at  
least one fiducial, thereby embedding the at least one fiducial and the at  
least one feature; and  
10           identifying the location of the at least one fiducial using X-rays.
2. The method of claim 1, wherein providing a metallic foil  
comprises:  
             providing a foil comprising copper.  
15
3. The method of claim 1, wherein forming at least one fiducial  
comprises:  
             forming at least one fiducial comprising tungsten.
- 20       4. The method of claim 3, wherein the at least one fiducial is formed  
from a paste containing:  
             glass; and  
             tungsten in excess of 53% by weight.
- 25       5. The method of claim 3, wherein:  
             a dried print thickness of the at least one fiducial is at least 15  
microns.
- 30       6. The method of claim 1, wherein:  
             forming at least one feature and forming at least one fiducial  
comprise at least one firing step.
7. The method of claim 1, wherein:

forming at least one fiducial comprises curing of a thick-film polymer paste.

8. The method of claim 1, further comprising:  
5 applying a second foil to the dielectric before identifying the location of the at least one fiducial;  
forming at least one register hole in the innerlayer panel according to the identified location of the at least one fiducial;  
positioning a photo-tool according to the location of the at least  
10 one register hole;  
imaging the foils with the photo-tool; and  
etching the foils, wherein etching results in terminations for the embedded at least one feature.

15 9. The method of claim 1, wherein:  
the at least one feature comprises at least one capacitor or resistor.

10. The method of claim 1, further comprising:  
applying an encapsulant over the at least one fiducial prior to  
20 applying the dielectric.

11. The method of claim 10, wherein:  
the dielectric is a prepreg.

25 12. A printed wiring board comprising a plurality of stacked innerlayer panels formed by the method of claim 1.

13. An innerlayer panel, comprising:  
a dielectric;  
30 at least one feature at least partially embedded within the dielectric;  
at least one fiducial at least partially embedded within the dielectric, the fiducial comprising at least one element selected from the group consisting of: tungsten, tantalum, gold, iridium, rhenium, osmium, uranium and platinum; and

at least one conductive termination or associated circuitry in  
contact with the dielectric and electrically coupled to the at least one feature.

- 5           14.     The innerlayer panel of claim 13, wherein:  
              the at least one fiducial further comprises glass.
15.     The innerlayer panel of claim 13, wherein:  
              the at least one feature comprises at least one of a capacitor and a  
10           resistor.
16.     The innerlayer panel of claim 13, further comprising:  
              an encapsulant disposed between the at least one feature and the  
              dielectric.
- 15           17.     A printed wiring board comprising a plurality of stacked innerlayer  
              panels of claim 13.